

DECLARATION OF INVENTOR FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled: METHODS FOR FORMING AND INTEGRATED CIRCUIT STRUCTURES CONTAINING RUTHENIUM AND TUNGSTEN CONTAINING LAYERS, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56.

PRIOR FOREIGN APPLICATIONS:

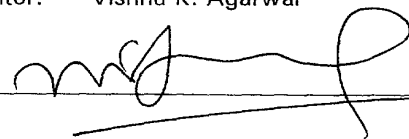
I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued therefrom.

* * * * *

Full Name of Sole or first Inventor: Vishnu K. Agarwal

Inventor's Signature



3rd May, 2000

Date

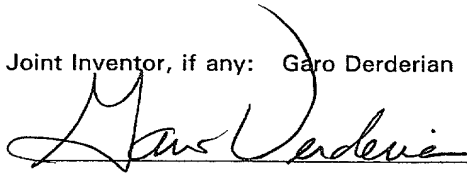
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Inventor's Signature



5/1/00

Date

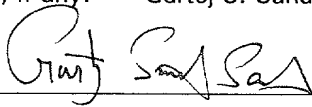
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Full Name of Third Joint Inventor, if any: Gurtej S. Sandhu

Inventor's Signature



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Date

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Full Name of Fourth Joint Inventor, if any: Weimin M. Li

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5/1/2000

Date

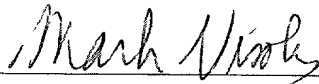
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Cem Basceri

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Sam Yang

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Art Unit --

Vishnu K. Agarwal, Garo Derderian, Gurtej
 S. Sandhu, Weimin M. Li, Mark Visokay,
 Cem Basceri, Sam Yang
 Application No.: --

Filed: Herewith

For: METHODS FOR FORMING AND
 INTEGRATED CIRCUIT
 STRUCTURES CONTAINING
 RUTHENIUM AND TUNGSTEN
 CONTAINING LAYERS

Examiner: --

POWER OF ATTORNEY BY ASSIGNEE AND
CERTIFICATE BY ASSIGNEE UNDER 37 CFR § 3.73(b)

TO THE ASSISTANT COMMISSIONER FOR PATENTS
 Washington, DC 20231

Sir:

MICRON TECHNOLOGY, INC., the Assignee of the entire right, title and interest in the above-identified patent application by assignment attached hereto, hereby appoints the attorneys and agents of the firm of KLARQUIST SPARKMAN CAMPBELL LEIGH & WHINSTON, LLP, listed as follows:

Name	Reg. No.	Name	Reg. No.
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CALDWELL, Lisa M.	41,653	PETERSEN, David P.	28,106
DeGRANDIS, Paula A.	43,581	POLLEY, Richard J.	28,107
GEORGE, Samuel E.	44,119	SCOTTI, Robert F.	39,830
GIRARD, Michael P.	38,467	SIEGEL, Susan Alpert	43,121
HARDING, Tanya M.	42,630	SLATER, Stacey C.	36,011
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JOHNSON, Michelle L.	36,352	STUART, John W.	24,540
JONES, Michael D.	41,879	VANDENBERG, John D.	31,312
KLARQUIST, Kenneth S.	16,445	WHINSTON, Arthur L.	19,155
KLITZKE II, Ramon A.	30,188	WIGHT, Stephen A.	37,759
LEIGH, James S.	20,434	WINN, Garth A.	33,220
MAURER, Gregory L.	43,781		

and also attorneys Michael L. Lynch (Reg. No. 30,871), Lia M. Pappas (Reg. No. 34,095), W. Eric Webostad (Reg. No. 35,406) and Charles Brantley (Reg.

No. 38,086) of Micron Technology, Inc., as its attorneys with full power of substitution to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.


The Assignee certifies that the above-identified Assignment has been reviewed and to the best of Assignee's knowledge and belief, title is in the Assignee, and a copy of the Assignment is submitted herewith.

Please direct all correspondence regarding this application to:

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MICRON TECHNOLOGY, INC.

Date: 5/9/00 By: 
Name: Michael L. Lynch, Esq.
Title: Chief Patent Counsel

Attachment: Copy of Assignment; Copy of Board of Directors' Resolution